Product Change Notification

Change Notification #:	**114894 - 00**
Change Title:	**Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Low Profile 100HFA016LS,** **Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Standard 100HFA016FS** **PCN 114894-00, Product Design,** **Firmware Revision**
Date of Publication:	**September 16, 2016**

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Sep 09, 2016

Description of Change to the Customer:

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Affected Product Code	Product Description
100HFA016LS	Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Low Profile 100HFA016LS
100HFA016FS	Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Standard 100HFA016FS

Overview of Changes:

Change 1: The UEFI firmware version shall be changed from 0x15 to 0x1C.

Change 2: The Thermal Monitoring firmware version shall be changed from 10.0.0.0.696 to 10.1.0.0.101.

Change 3: The CONFIG image will be updated from 10.0.0.991.51 to 10.1.0.0.129

Product Material Change Details:

Change 1: UEFI ROM image 0x15 will be replaced with UEFI ROM image 0x1C. UEFI ROM image 0x1C introduces updates that enable use of the UNDI driver.

- Updating OptionROM functionality to include UNDI driver.
- Replacing HfiPCieGen3.rom file with HfiUndiStub.rom in the -o option ROM partition
- Replacing hfi1_fabric_boot.efi file with HfiPcieGen3.efi in the -b bulk partition

Change 2: Thermal Monitoring (TMM) configuration image 10.0.0.0.696 will be replaced with 10.1.0.0.101. TMM image 10.1.0.0.101 adds enhanced Active Optical Cable thermal monitoring (MCTP/PLDM).

Change 3: The CONFIG image was updated to report versions and match up with the IFS release version.

Customer Impact of Change and Recommended Action:

Intel is not recommending additional qualification of these changes by customers.
There is no change to the adapter Intel Material Master (MM) numbers.
Please contact your local Intel Field Sales Representative if you have any questions about this change.
Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change MM Rev	Post change MM Rev	Pre Change TA	Post Change TA	Pre Change AS	Post Change AS	Pre Change PBA	Post Change PBA
100HFA016FS	945671	01	02	J29320-001	J29320-002	J29321-001	J29321-002	J10547-017	J10547-019
100HFA016LS	948159	11	12	J10549-020	J10549-021	J10548-020	J10548-021	J10547-017	J10547-019

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
September 16, 2016	00	Originally Published PCN

Product Change Notification

114894 - 00

INFORMATION IN THIS DOCUMENT IS PROVIDED IN CONNECTION WITH INTEL PRODUCTS. NO LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT. EXCEPT AS PROVIDED IN INTEL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, INTEL ASSUMES NO LIABILITY WHATSOEVER AND INTEL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY, RELATING TO SALE AND/OR USE OF INTEL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

A "Mission Critical Application" is any application in which failure of the Intel Product could result, directly or indirectly, in personal injury or death. SHOULD YOU PURCHASE OR USE INTEL'S PRODUCTS FOR ANY SUCH MISSION CRITICAL APPLICATION, YOU SHALL INDEMNIFY AND HOLD INTEL AND ITS SUBSIDIARIES, SUBCONTRACTORS AND AFFILIATES, AND THE DIRECTORS, OFFICERS, AND EMPLOYEES OF EACH, HARMLESS AGAINST ALL CLAIMS COSTS, DAMAGES, AND EXPENSES AND REASONABLE ATTORNEYS' FEES ARISING OUT OF, DIRECTLY OR INDIRECTLY, ANY CLAIM OF PRODUCT LIABILITY, PERSONAL INJURY, OR DEATH ARISING IN ANY WAY OUT OF SUCH MISSION CRITICAL APPLICATION, WHETHER OR NOT INTEL OR ITS SUBCONTRACTOR WAS NEGLIGENT IN THE DESIGN, MANUFACTURE, OR WARNING OF THE INTEL PRODUCT OR ANY OF ITS PARTS.

Intel may make changes to specifications and product descriptions at any time, without notice. Designers must not rely on the absence or characteristics of any features or instructions marked "reserved" or "undefined". Intel reserves these for future definition and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to them. The information here is subject to change without notice. Do not finalize a design with this information.

The products described in this document may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com
Asia Pacific/PRC Contact: apacgccb@intel.com
Europe Email: eccb@intel.com
Japan Email: jccb.ijkk@intel.com

Copyright © Intel Corporation 2016. Other names and brands may be claimed as the property of others.

BunnyPeople, Celeron, Celeron Inside, Centrino, Centrino Inside, Cilk, Core Inside, i960, Intel, the Intel logo, Intel AppUp, Intel Atom, Intel Atom Inside, Intel Core, Intel Inside, Intel Insider, the Intel Inside logo, Intel NetBurst, Intel NetMerge, Intel NetStructure, Intel SingleDriver, Intel SpeedStep, Intel Sponsors of Tomorrow, the Intel Sponsors of Tomorrow logo, Intel StrataFlash, Intel vPro, Intel XScale, InTru, the InTru logo, the InTru Inside logo, InTru soundmark, Itanium, Itanium Inside, MCS, MMX, Moblin, Pentium, Pentium Inside, Puma, skoool, the skoool logo, Sound Mark, The Creators Project, The Journey Inside, Thunderbolt, vPro Inside, VTune, Xeon, and Xeon Inside are trademarks of Intel Corporation in the U.S. and/or other countries.

Learn how to use Intel Trademarks and Brands correctly at http://www.intel.com/intel/legal/tmusage2.htm.